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THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of)
MAEDA et al) Art Unit: 2829
Serial No.: 09/808,016) Examiner: Kilday
Filed: March 15, 2001)
For: FILM-FORMING SURFACE)
REFORMING METHOD AND)
SEMICONDUCTOR DEVICE)
MANUFACTURING METHOD)

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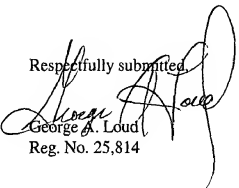
Sir:

Submitted herewith is a copy of an office action received from the Japanese Patent Office in connection with Japanese Application No. 2001-001759, together with a partial translation thereof. Also submitted herewith are copies of three Japanese Kokai Publications cited as document numbers 1, 2 and 5 in the Japanese office action of April 22, 2003 and listed on the attached PTO-A820. Also enclosed are published English language abstracts for each of the three Japanese Kokai Publications submitted here. The documents referred to in the Japanese office action of April 22, 2003 identified as document numbers 3 and 4 are already of record in the captioned application.

CERTIFICATION

The undersigned hereby certifies that each item of information contained in this Information Disclosure Statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three (3) months prior to the filing of this Information Disclosure Statement.

Respectfully submitted,


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Dated: July 9, 2003

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(Use several sheets if necessary)

JUL 09 2003

SERIAL NO. 09/808,016

FILING

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GROUP

U.S. PATENT DOCUMENTS

[illegible]

FOREIGN PATENT DOCUMENTS

[illegible]

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.